

AF 12815

AMENDMENT TRANSMITTAL LETTER			Docket No. M4065.0477/P477
-------------------------------------	--	--	-------------------------------

Application No. 09/939,636-Conf. #4394	Filing Date August 28, 2001	Examiner J. Nguyen	Art Unit 2815
---	--------------------------------	-----------------------	------------------

Applicant(s): Kevin M. Devereaux

Invention: METHOD AND APPARATUS FOR WAFER LEVEL TESTING OF SEMICONDUCTOR USING SACRIFICIAL ON DIE POWER AND GROUND METALIZATION


TO THE COMMISSIONER FOR PATENTS

Transmitted herewith is an amendment in the above-identified application.

The fee has been calculated and is transmitted as shown below.

CLAIMS AS AMENDED					
	Claims Remaining After Amendment	Highest Number Previously Paid	Number Extra Claims Present	Rate	
Total Claims	19	- 24 =		x	0.00
Independent Claims	3	- 3 =		x	0.00
Multiple Dependent Claims (check if applicable) <input type="checkbox"/>					
Other fee (please specify):					
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT:					00.00

- ☒ Large Entity ☐ Small Entity
- ☒ No additional fee is required for this amendment.
- ☐ Please charge Deposit Account No. _____ in the amount of \$ _____.
A duplicate copy of this sheet is enclosed.
- ☐ A check in the amount of \$ _____ to cover the filing fee is enclosed.
- ☐ Payment by credit card. Form PTO-2038 is attached.
- ☒ The Director is hereby authorized to charge and credit Deposit Account No. 04-1073 as described below. A duplicate copy of this sheet is enclosed.
- ☒ Credit any overpayment.
- ☒ Charge any additional filing or application processing fees required under 37 CFR 1.16 and 1.17.


Thomas J. D'Amico
Attorney Reg. No.: 28,371

Dated: June 4, 2003

DICKSTEIN SHAPIRO MORIN & OSHINSKY LLP
2101 L Street NW
Washington, DC 20037-1526
(202) 828-2232

RECEIVED
JUN - 9 2003
TECHNOLOGY CENTER 2800



Docket No.: M4065.0477/P477

(PATENT)

#11
Amot
B
(NE)
6-10-03
onej

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Kevin M. Devereaux

Application No.: 09/939,636

Group Art Unit: 2815

Filed: August 28, 2001

Examiner: J. Nguyen

For: METHOD AND APPARATUS FOR WAFER
LEVEL TESTING OF SEMICONDUCTOR
USING SACRIFICIAL ON DIE POWER
AND GROUND METALIZATION

AMENDMENT UNDER 37 C.F.R. 1.116, REQUEST FOR
RECONSIDERATION AND REQUEST FOR WITHDRAWAL OF FINAL
REJECTION STATUS

Box AF
Commissioner for Patents
Washington, DC 20231

Dear Sir:

In response to the Office Action dated March 4, 2003 (Paper No. 10) finally rejecting claims 1-11 and 25-32, please amend the above-identified U.S. patent application as follows:

In the Claims

Please rewrite claim 1, 9, 10 and 25 as follows:

1. (Currently Amended) A semiconductor wafer comprising:

at least one first sacrificial conductive line for supplying a first voltage to a plurality of dies fabricated on said wafer;

RECEIVED
JUN -9 2003
TECHNOLOGY CENTER 2800